Noti	fication Number	20161	1003002	Notification	Dat	te:	October 21, 2016	
Title	Datasheet fo	r TL1963	A-Q1					
Customer Contact: PCN Manager			ager		Dept:		Quality Services	
Cha	nge Type:		-				• •	
	Assembly Site		Design			Wafer	Bump Site	
	Assembly Process		Data Sheet			Wafer Bump Material		
	Assembly Materials		Part number	change		Wafer Bump Process		
Mechanical Specification		Test Site			Wafer Fab Site			
Packing/Shipping/Labeling		Test Process			Wafer	Fab Materials		
						Wafer	Fab Process	
Notification Details								
Description of Change:								
Texas Instruments Incorporated is announcing an information only notification.								
The	product datasheet	(s) is upd	lated as seen in the c	hange revisio	n hi	story b	elow:	
TEXAS INSTRUMENTS								
SLVSA	A79A – APRIL 2010–REVISED S	EPTEMBER 20	016				www.ti.com	
Chan	ges from Original (April	2010) to Re	evision A				Page	
Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section								
http://www.ti.com/lit/ds/symlink/tl1963a-q1.pdf Reason for Change:								
	nore accurately ref	lect devic	ce characteristics.					
	, ,			ity or Polishi	ili+-	(noci	tive (negative);	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
TL1963AQKTTRQ1								
1613								
For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.								

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com